

# **N-Channel Power MOSFET**

900V, 9.0A, 1.4Ω

#### **FEATURES**

- 100% Avalanche Tested
- G-S ESD Protection Diode Embedded
- Pb-free plating
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

KEY PERFORMANCE PARAMETERS				
PARAMETER	VALUE	UNIT		
V <sub>DS</sub>	900	V		
R <sub>DS(on)</sub> (max)	1.4	Ω		
$Q_g$	72	nC		

### **APPLICATION**

- Power Supply
- Lighting



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> =25°C unless otherwise noted)					
PARAMETER		SYMBOL	TO-220	ITO-220	UNIT
Drain-Source Voltage		$V_{DS}$	90	00	V
Gate-Source Voltage		$V_{GS}$	±	30	V
Continuous Drain Current (Note 1) $T_{C} = 25^{\circ}C$ $T_{C} = 100^{\circ}C$	;= 25°C	ı	9.0		А
	= 100°C	I <sub>D</sub>	5.7		
Pulsed Drain Current (Note 2)		I <sub>DM</sub>	3	6	А
Total Power Dissipation @ T <sub>C</sub> = 25°C		P <sub>DTOT</sub>	290	89	W
Single Pulsed Avalanche Energy (Note 3)		E <sub>AS</sub>	454		mJ
Single Pulsed Avalanche Current (Note 3)		I <sub>AS</sub>	9		А
Operating Junction and Storage Temperature Range		$T_J,T_STG$	- 55 to +150		°C

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	TO-220	ITO-220	UNIT
Junction to Case Thermal Resistance	R <sub>eJC</sub>	0.43 1.4		°C/W
Junction to Ambient Thermal Resistance	R <sub>OJA</sub>	62.5		°C/W

**Notes:**  $R_{\text{BJA}}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\text{BJA}}$  is guaranteed by design while  $R_{\text{BCA}}$  is determined by the user's board design.  $R_{\text{BJA}}$  shown below for single device operation on FR-4 PCB with minimum recommended footprint in still air.



<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 4)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV <sub>DSS</sub>	900			V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	$V_{GS(TH)}$	2.0		4.0	V
Gate Body Leakage	$V_{GS} = \pm 30V, V_{DS} = 0V$	I <sub>GSS</sub>			±100	μA
Zero Gate Voltage Drain Current	$V_{DS} = 900V, V_{GS} = 0V$	I <sub>DSS</sub>		1	10	μA
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 4.5A$	R <sub>DS(on)</sub>		1.13	1.4	Ω
Dynamic (Note 5)						
Total Gate Charge		$Q_{g}$		72	<u></u>	nC
Gate-Source Charge	$V_{DS} = 720V, I_{D} = 9.0A,$	$Q_gs$		11		
Gate-Drain Charge	$V_{GS} = 10V$	$Q_{gd}$		31		
Input Capacitance		C <sub>iss</sub>		2470		
Output Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$ f = 1.0MHz	Coss		192		pF
Reverse Transfer Capacitance	1 = 1.0IVIM2	C <sub>rss</sub>		27		
Switching (Note 6)						
Turn-On Delay Time		t <sub>d(on)</sub>		52		
Turn-On Rise Time	$V_{DD} = 450V$ ,	t <sub>r</sub>		97		
Turn-Off Delay Time	$R_{GEN} = 25\Omega$ , $I_D = 9.0A$ , $V_{GS} = 10V$ ,	t <sub>d(off)</sub>		212		ns
Turn-Off Fall Time	1D = 9.0A, VGS = 10V,	t <sub>f</sub>		159		
Source-Drain Diode (Note 4)						
Forward On Voltage	I <sub>S</sub> = 9.0A, V <sub>GS</sub> = 0V	$V_{SD}$			1.5	V
Reverse Recovery Time	$V_{GS} = 0V, I_{S} = 9A,$	t <sub>fr</sub>		570		ns
Reverse Recovery Charge	dl <sub>F</sub> /dt = 100A/us	$Q_{fr}$		6.6		μC

#### Notes:

- Current limited by package
- 2. Pulse width limited by the maximum junction temperature
- 3. L = 10.6mH,  $I_{AS}$  = 9A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C 100% Eas Test Condition: L = 10.6mH,  $I_{AS}$  = 4.5A,  $V_{DD}$  = 50V,  $R_{G}$  = 25 $\Omega$ , Starting  $T_{J}$  = 25 $^{\circ}$ C
- 4. Pulse test: PW ≤ 300µs, duty cycle ≤ 2%
- 5. For DESIGN AID ONLY, not subject to production testing.
- 6. Switching time is essentially independent of operating temperature.



### **ORDERING INFORMATION**

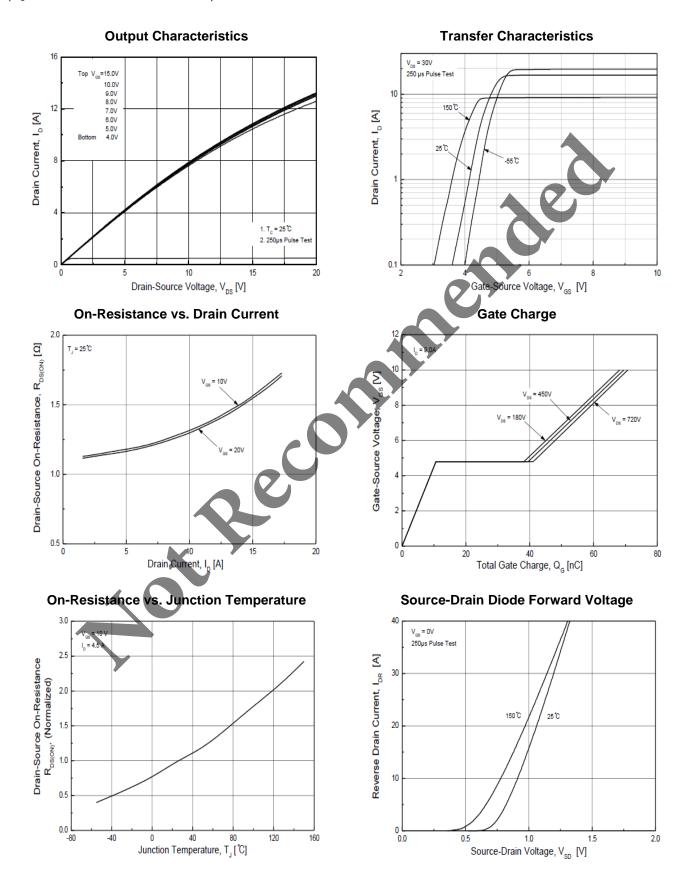
PART NO.	PACKAGE	PACKING
TSM9N90ECZ C0G	TO-220	50pcs / Tube
TSM9N90ECI C0G	ITO-220	50pcs / Tube





## **CHARACTERISTICS CURVES**

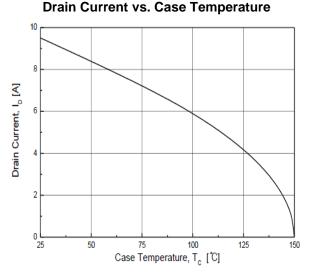
 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 



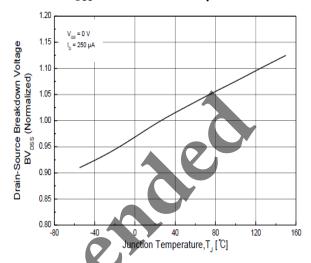


### **CHARACTERISTICS CURVES**

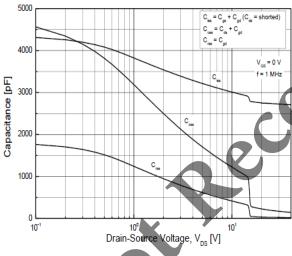
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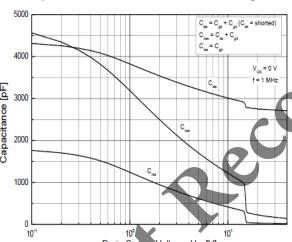


### BV<sub>DSS</sub> vs. Junction Temperature

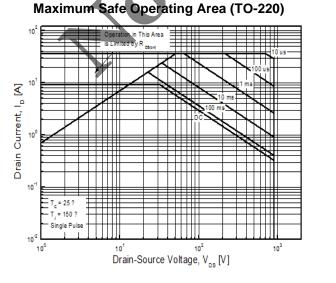


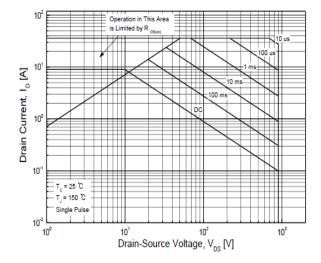
### Capacitance vs. Drain-Source Voltage





## Maximum Safe Operating Area (ITO-220)



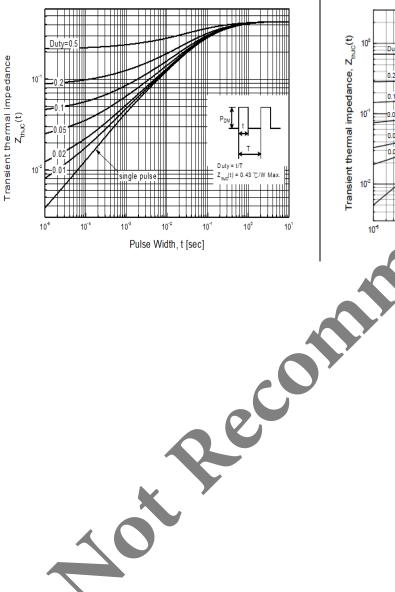




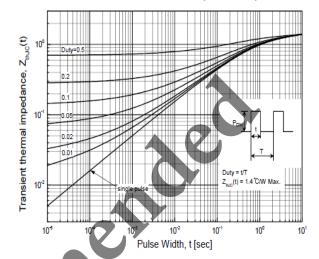
## **ELECTRICAL CHARACTERISTICS CURVES**

 $(T_C = 25^{\circ}C \text{ unless otherwise noted})$ 

## Normalized Thermal Transient Impedance, Junction-to-Ambient (TO-220)

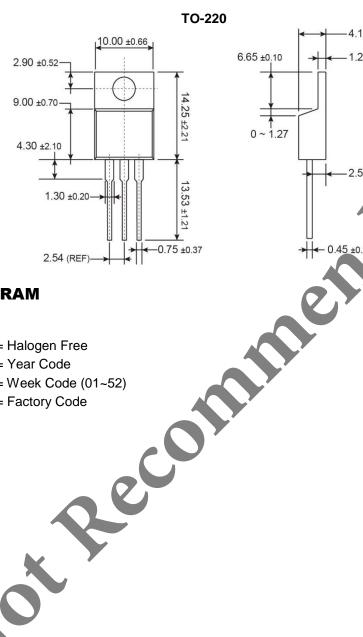


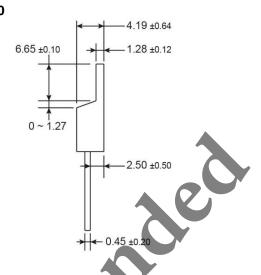
## Normalized Thermal Transient Impedance, Junction-to-Ambient (ITO-220)



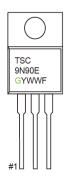


## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)





### **MARKING DIAGRAM**



= Halogen Free

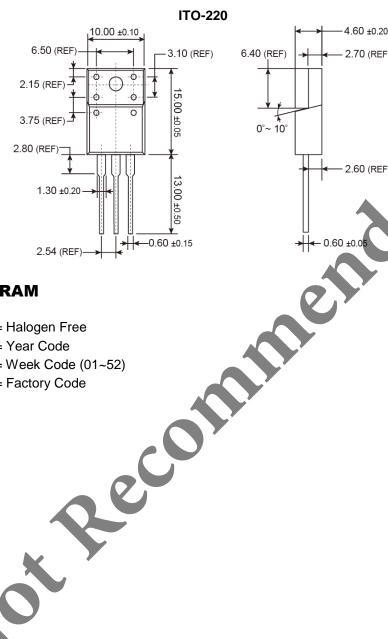
Y = Year Code

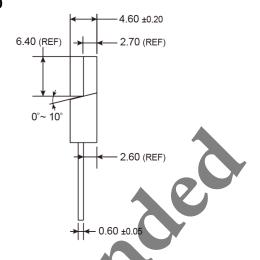
**WW** = Week Code (01~52)

= Factory Code

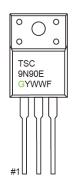


## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)





## **MARKING DIAGRAM**



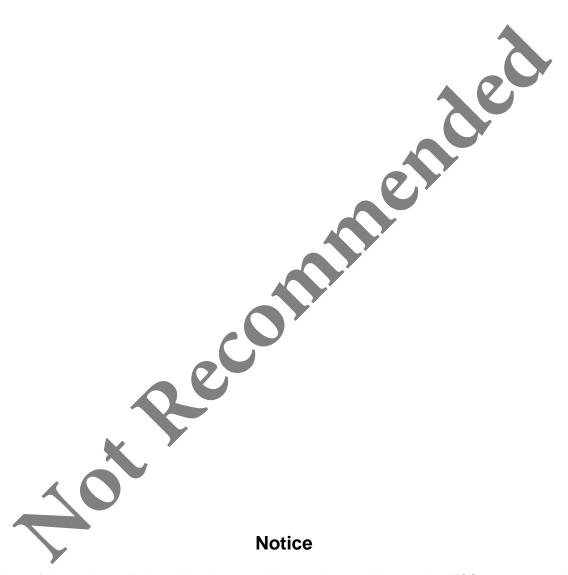
= Halogen Free

= Year Code

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= Factory Code





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